

10. A method according to one of the preceding claims, characterised in that the antenna wire is fixed on the substrate using a non conductive wire (19).

5 11. A method according to one of the preceding claim, characterised in that the antenna wire is a hybrid wire (22) associated with at least one non conductive wire.

10 12. A method according to the preceding claim, characterised in that the non conductive wire (19) surrounds the antenna wire at least in places.

13. A method according to one of claims 11 to 12, characterised in that the non conductive wire (19) is thermo-fusible or thermoplastic.

15 14. A method according to claim 10, characterised in that the technique for fixing a conductive wire to the substrate is selected among sewing, embroidery, inlay.

20 15. A device including an antenna (3) connected to contact pads (5, 6), said device including a substrate and an antenna provided with connection terminal sections (7b, 8b) resting on the substrate (2, 2b, 2f, 1b),

25 said antenna being connected by a soldering (38) to the terminal sections, characterised in that the electric contact pads have a surface (40) facing a antenna connection terminal section (7b, 8b), said section being positioned on the substrate.

30 16. A device according to claim 15, characterised in that the antenna (3) is produced by embroidery or sewing on a flexible support (2f) including a fabric

and in that it includes a reinforcing material (15) in the form of a sheet or a layer on a face of the substrate opposite the one supporting the terminal sections.

5           17. A device according to one of claims 15 or 16, characterised in that it includes a cavity (26) in the substrate and/or the reinforcing sheet or layer close to the antenna connection terminal sections.

10           18. A device according to claim 17, characterised in that the contact pads are associated with a microcircuit (20) and facing the substrate and the antenna terminal sections resting on the substrate whereas the microcircuit is inserted at least partially into the cavity (26).

15           19. A device according to one of claims 15 to 18, characterised in that the pads include a soldering mark (30) across the pads on a face of the pads opposite the soldered one.

20           20. A device according to claim 15 to 19, characterised in that it includes perforations (17) in the reinforcing material opposite each of the connected terminal section.

25           21. A device according to claims 15 to 20, characterised in that the antenna wire is a hybrid wire (22) associated with at least one non conductive wire.

          22. A device according to claim 15 to 21, characterised in that the non conductive wire is thermo-fusible or thermoplastic.

30           23. A radio frequency communication electronic product such as a contactless chip card, a passport

containing the device according to one of claims 15 to 22.

10. A method according to one of the preceding claims, characterised in that the antenna wire is fixed on the substrate using a non conductive wire (19).

5 11. A method according to one of the preceding claim, characterised in that the antenna wire is a hybrid wire (22) associated with at least one non conductive wire.

10 12. A method according to the preceding claim, characterised in that the non conductive wire (19) surrounds the antenna wire at least in places.

13. A method according to one of claims 11 to 12, characterised in that the non conductive wire (19) is thermo-fusible or thermoplastic.

15 14. A method according to claim 10, characterised in that the technique for fixing a conductive wire to the substrate is selected among sewing, embroidery, inlay.